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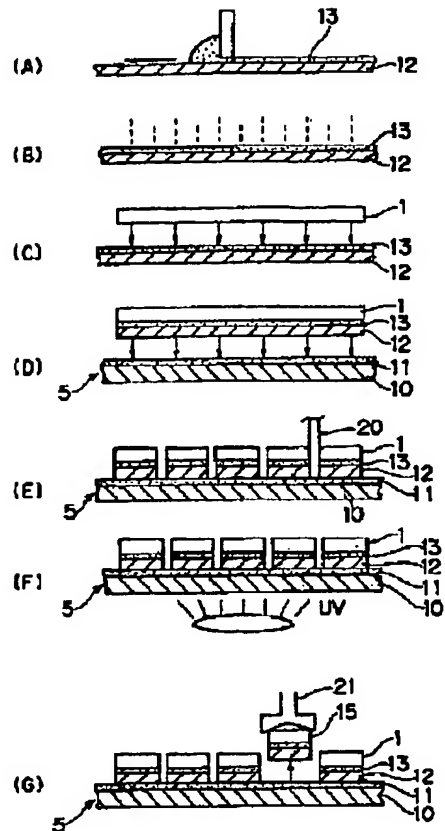
APPLICATION DATE : 13-08-97
APPLICATION NUMBER : 09231794

APPLICANT : TEXAS INSTR JAPAN LTD;

INVENTOR : AMAMI MASAZUMI;

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TITLE : MANUFACTURE OF
SEMICONDUCTOR DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To manufacture a semiconductor device provided with a stress blocking board under a semiconductor chip for preventing the deterioration of mounting yield, owing to thermal stress with less man-hour.

SOLUTION: A suitable method for manufacturing the semiconductor chip provided with the stress blocking board is provided. The method is provided with a process for preparing a dicing tape 5, having the stress blocking board 12 constituted of the material of high elasticity and an adhered face 11, a process for making the semiconductor wafer 1 adhere to the stress blocking board 12 through an adhered layer 13, a process for making the stress blocking board 12 adhere on the adhered face 11 of the dicing tape, a process for cutting the semiconductor wafer 1 with the stress blocking board 12 in the unit of the individual semiconductor chips and a process for peeling off the semiconductor chip 15 and the stress insulating board 12, which are cut, from the dicing tape 5. Since the stress blocking board 12 is cut with the semiconductor wafer 1, it is not necessary to cut and supply the stress blocking boards 12 later by adjusting them to the semiconductor chips of different sizes.

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